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5050863-8 Product Details



5050863-8

Discrete Sockets

Home > Products > Socket/Card Products > Product Feature Selector > Product Details

Always EU RoHS/ELV Compliant (Statement of Compliance)

Product Highlights:

- Mini-Spring Socket Product Line
- · Board-to-Board, Wire-to-Board
- . Applies To Wire/Cable, Applies To Printed Circuit Board
- Contact Rated Current = 5 A
- Wire/Cable Size = .081 .326 mm²

View all Features

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- Pricing & Availability
- Search for Tooling
- Product Feature Selector

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Contact Us About This Product

TE Internal Number: 5050863-8











Documentation & Additional Information

Product Drawings:

MINIATURE SPRING SOCKET ASSEMBLY SERIES 2 (PDF, English)

Catalog Pages/Data Sheets:

None Available

Product Specifications:

None Available

Application Specifications:

None Available

Instruction Sheets:

None Available

CAD Files: (CAD Format & Compression Information)

- 2D Drawing (DXF, Version 0)
- 3D Model (IGES, Version O)
- 3D Model (STEP, Version O)

Additional Information:

· Product Line Information

Related Products:

Tooling



Product Features (Please use the Product Drawing for all design activity)

Product Type Features:

- Product Line = Mini-Spring Socket
- Socket Length (mm [in]) = 6.60 [0.260]
- Sleeve Style = Closed Bottom
- Sealant = Without
- Wire/Cable Type = Discrete Wire
- Termination Method to Wire/Cable = Solder
- Termination Method to PC Board = Through Hole Press Fit
- Product Series = 3

Electrical Characteristics:

- Sleeve Material = Copper
- Profile = Zero

Contact Base Material = Beryllium Copper

List all Documents

Contact Features:

Industry Standards:

Contact Plating, Mating Area, Material = Tin

Contact Spring Plating = Tin

Contact Type = Socket

- Government/Industry Qualification = No. RoHS/ELV Compliance = RoHS compliant, ELV compliant
 - Lead Free Solder Processes = Wave solder capable to 240°C, Wave solder capable to 260°C, Wave solder capable to 265°C, Reflow solder capable to 245°C, Reflow solder capable to 260°C, Pin-in-Paste capable to 245°C, Pin-in-Paste capable to 260°C

Contact Plating, Mating Area, Thickness (μm [μin]) = 0.00254 [0.1]

RoHS/ELV Compliance History = Always was RoHS compliant

Operating Temperature (°C [°F]) = -65 - +126 [-85 - +258]

Termination Features:

- Wire/Cable Size (mm²) = 0.081 0.326
- Wire/Cable Size (AWG) = 22 28

Contact - Rated Current (A) = 5

Insertion Method = Hand/Semi-Automatic

Dimensions:

- Recommended Hole Size (mm [in]) = 1.32 [0.052]
- PCB Thickness, Recommended (mm [in]) = 0.79 3.18 [0.031 -0.125

Body Features:

- Mating Pin Dia. Range (mm [in]) = 0.36 0.66 [0.014 0.026]
- Sleeve Material Plating = Tin
- Wire Type = Solid
- Spring Material = Beryllium Copper

Conditions for Usage:

Environmental:

Applies To = Wire/Cable, Printed Circuit Board

Operation/Application:

- Application Use = Board-to-Board, Wire-to-Board
- Contact Transmits (Typical Application) = Signal (Data)/Power
- Application = Production

Packaging Features:

- Packaging Method = Loose Piece
- Packaging Quantity = 2,000/Bag

Other:

Brand = AMP

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